

Frencken marks groundbreaking for facility expansion in Singapore with S\$63M in investment

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Strengthens position to deliver ultra-high precision and ultra-clean assemblies for analytical life sciences sectors



Frencken Group Limited, a global integrated technology solutions company, held a groundbreaking ceremony for its upcoming manufacturing facility in Singapore. The new facility expands and consolidates the Group's Mechatronics operations in Singapore into a larger and more efficient facility.

Construction of the New Facility is slated to start in the third quarter of 2025 and complete in the first quarter of 2027. Upon completion, the relocation and consolidation of Mechatronics Singapore's operations to the new site will be carried out in phases. Entailing an estimated development cost of around S\$63 million, the New Facility is expected to yield a gross floor area of 28,594 square metres which will be around 1.4 times the size of Mechatronics Singapore's current combined operations situated at Changi North and Seletar Aerospace Link. Mechatronics Singapore will be able to achieve the highest operational efficiency and quality assurance with this facility.

Lim Wee Lee, Director of JTC, and Mr Lionel Lim, Vice President and Head of Technology Hardware and Equipment of Singapore Economic Development Board (EDB) were present at Frencken's groundbreaking ceremony. The Group's non-executive Chairman, board of directors, customers and business partners, as well as management and employees were also at the site to commemorate this milestone.

Dennis Au, President of Frencken said, "The strategic initiative will set the stage for Mechatronics Singapore's next chapter of growth. Frencken's investment underscores our commitment and confidence in Singapore's ongoing growth into a significant and vibrant semiconductor hub."

"With the expanded manufacturing capacity and enhancement of its local capabilities, Frencken will be able to better serve global markets and high-growth industries like semiconductor and life sciences, from Singapore" said Lionel Lim, Vice President and Head, Technology Hardware and Equipment, EDB.

Wang Liang Horng, Managing Director and Vice President of Frencken Mechatronics Asia, said, "We are scaling up production capacity especially in cleanroom assembly which is projected to triple. This will enable Mechatronics Singapore to handle more high-IP and complex projects, and strengthen our position in the wafer fabrication equipment sector. We are investing in advanced technologies and equipment at the New Facility to enhance our core strengths, enabling us to deliver the ultra-high precision and ultra-clean assemblies required in the wafer fabrication equipment and analytical life sciences sectors."

Plans are underway to increase automation and invest in state-of-the-art equipment to enhance capabilities in high-precision engineering, such as submicron machining, as well as advanced cleaning. The new facility will also enable the Group to support increasing program transfers to Asia from its major semiconductor and analytical life sciences customers based in Europe.

"Our initiative to bolster our operations in Singapore dovetails the Group's ongoing technology and knowledge transfer initiatives between its Mechatronics operations in Europe and Asia. We aim to shape Mechatronics Singapore into a larger growth catalyst by reinforcing its foundation to pursue opportunities across our semiconductor, analytical life sciences and aerospace portfolios and drive the Group's mechatronics division," Au commented.